221 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

222 ■ These assemblies are ESD sensitive; ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

<table>
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<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-00400</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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<tbody>
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PLOT NAME = Top Assembly Drawing

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TEXAS INSTRUMENTS
**COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.**

**ASSEMBLY VARIANT: [No Variations]**

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<th>BOARD #: TIDA-00400</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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| PLOT NAME = Bottom Assembly Drawing | GENERATED : 12/2/2014 9:59:52 PM | TEXAS INSTRUMENTS |

**Diagram:**

- H5
- H7
- H6
- H8
- LBL1
- [Other components labeled as COH5, COH6, COH7, COH8, COLBL1, COLogo1, PAR901, PAR902, PAR903, PAR1001, PAR1002, PAR1101, PAR1102, PAR1103, PAR1201, PAR1202, COR9, COR10, COR11, COR12]
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